



BOARD PATTERN

NOTES:

- ①. MAT'L:
HOUSING: LCP
CONTACT: COPPER ALLOY

PLATING:
CONTACT: (SEE TABLE ON SHEET1)
SOLDER BALL: (SEE TABLE ON SHEET1)
EUTECTIC SnPb OR LEAD FREE
95.5Sn/4Ag/0.5Cu
- 2. OVERALL BOARD-TO-BOARD STACK HEIGHT WHEN MATED TO P/N 74213 (240 0mm PLUG) IS 6mm REF
- ③. PLATING FOR -2XX SERIES DASH NOS. IS Au OVER Ni WITH SPECIAL CONTACT GEOMETRY TO MEET REQUIREMENTS TELCORDIA GR-1217-CORE: CENTRAL OFFICE ENVIORNMENT
- ④. FOR PROPER APPLICATION FOLLOW FCI APPLICATION SPECIFICATION GS-20-033 LEAD FREE SOLDER BALLS WILL NOT SOLDER PROPERLY IN A LEADED SOLDER PROCESS DUE TO A HIGHER REFLOW TEMPERATURE. LEAD FREE PRODUCT IS THEREFORE NOT BACKWARDS COMPATIBLE WITH LEADED OR SOME SOLDERING APPLICATIONS. REFERENCE FCI APPLICATION SPECIFICATION
- ⑤. THIS PRODUCT MEETS EUROPEAN UNION DIRECTIVES AND OTHER COUNTRY REGULATIONS AS DESCRIBED IN GS-22-008 PRODUCT MEETING THIS DIRECTIVE IS IDENTIFIED IN THE LOT CODE NUMBER MARKED ON EACH PART BY HAVING AN "X" IN THE SEVENTH CHARACTER POSITION

A

A

B

B

mat'l. code		surface ASME Y14.5 ✓	tolerance ASME Y14.5	projection 	product family MEG-ARRAY
ltr	ecn no	dr	date	tolerances unless otherwise specified	title 6mm RECT. ASSY. 8x30= 240 POS.
D				angles X*3 XX*13 0° ±2'	mm scale 2:1
		dr	D.WAUGHEN	1.31.02	dwg no 55755 sheet 2 of 2 size A4 type CUSTOMER Drawing
		enr	J. KONTOS	1.31.02	
		chr	J. KONTOS	1.31.02	
		appd	J. KONTOS	1.31.02	
sheet index	revision sheet				